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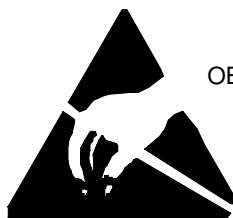
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Http://www.marktechopto.com

SPECIFICATION

PART NO. : MTBL2410-G-A

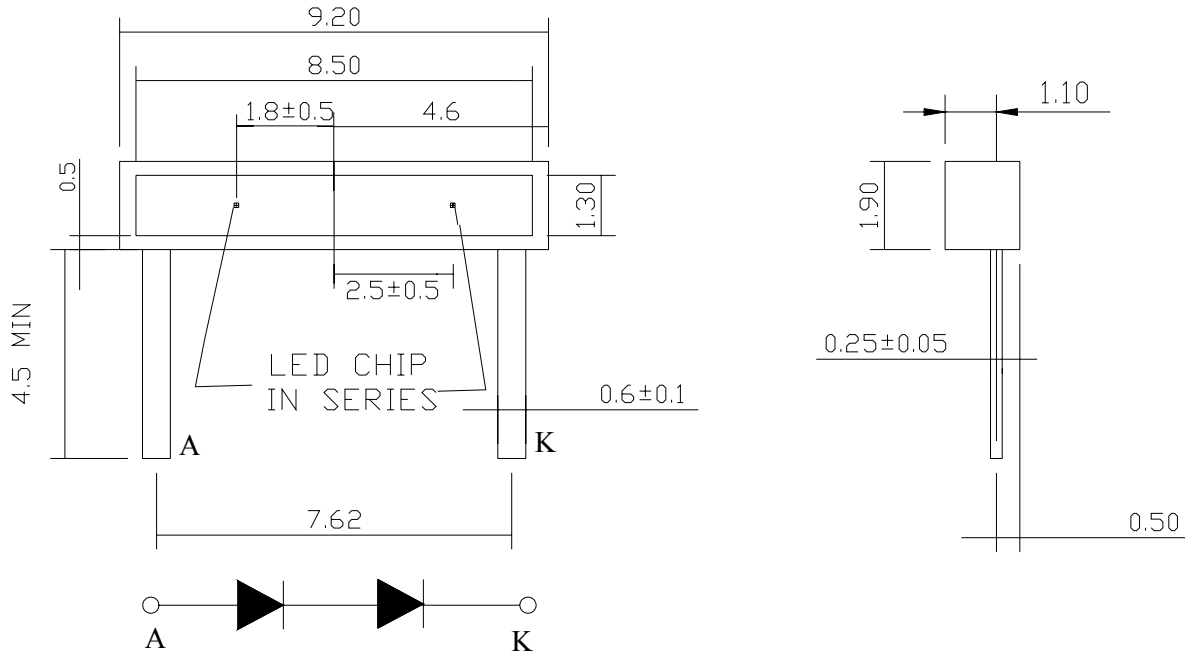
1.9 x 9.2mm SIDE VIEW LAMP



ATTENTION

OBSERVE PRECAUTION
FOR HANDLING
ELECTRO STATIC
SENSITIVE
DEVICES

Package Dimensions



Notes:

1. ALL DIMENSIONS ARE IN mm.
2. TOLERANCE IS ±0.25mm UNLESS OTHERWISE NOTED.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
MTBL2410-G-A	GaP/GaP	Green	Green Clear

Absolute Maximum Ratings at Ta=25°C

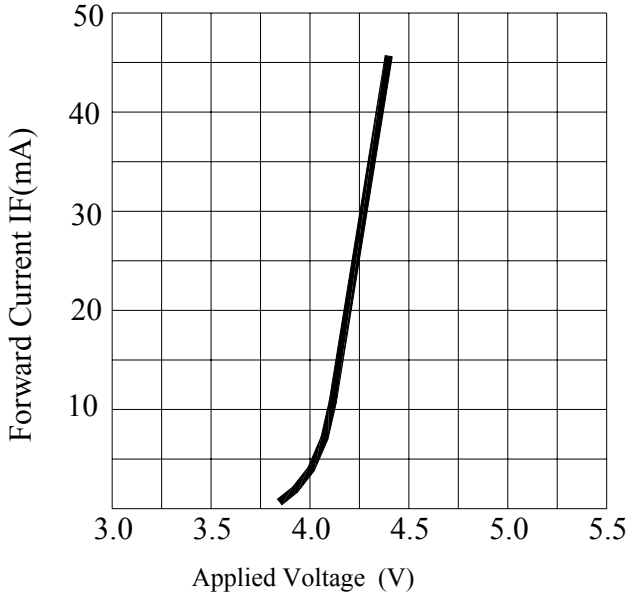
Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	156	mW
Reverse Voltage	V _R	10	V
D.C. Forward Current	I _f	30	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	100	mA
Operating Temperature Range	T _{opr.}	-25 to +85	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C
Lead Soldering Temp. (1.6mm from body) for 5 seconds.		260	°C

Electrical and Optical Characteristics:

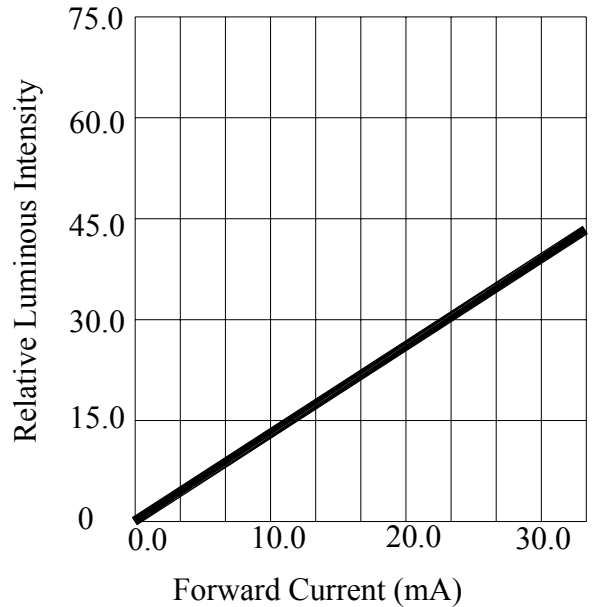
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =20mA	13.5	25		mcd
Forward Voltage	V _f	I _f =20mA		4.2	5.2	V
Peak Wavelength	λ _P	I _f =20mA		567		nm
Dominant Wavelength	λ _D	I _f =20mA		572		nm
Reverse Current	I _r	V _r =10V			100	μA
Viewing Angle	2θ 1/2	I _f =20mA		50		deg
Spectrum Line Halfwidth	Δλ	I _f =20mA		30		nm

NOTE: THE DATAS TESTED BY IS TESTER

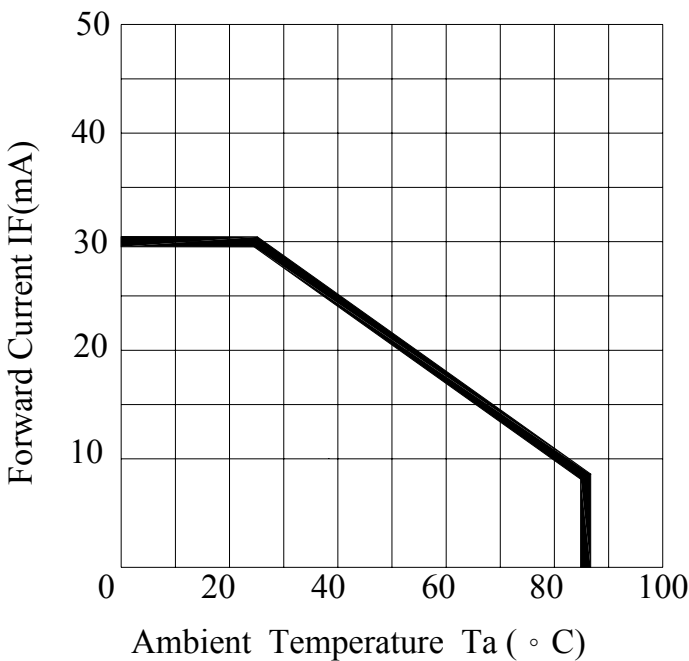
**Typical Electrical/Optical Characteristic Curves
(25°C Ambient Temperature Unless Otherwise Noted)**



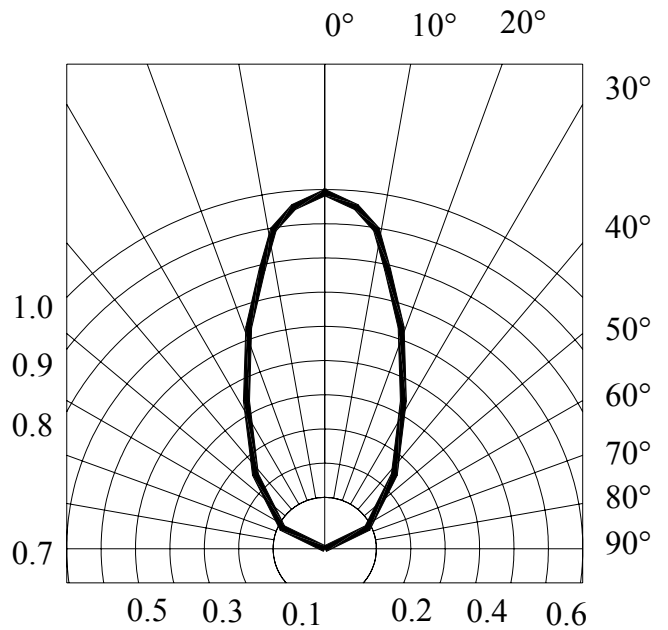
Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature vs. Forward Current



Radiation Diagram

PRECAUTION IN USE

Storage

Recommended storage environment

Temperature: 5°C ~ 30°C (41°F ~ 86°F)

Humidity: 60% RH Max.

Use within 3 days after opening of sealed vapor/ESD barrier bags.

Fold the opened bag firmly and keep in dry environment.

Soldering

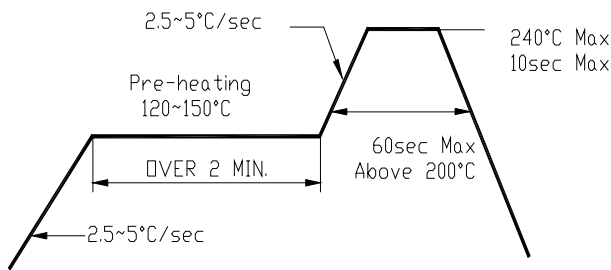
	Reflow Soldering		Hand Soldering	
	Lead Solder	Lead – free Solder	Temperature	350°C Max
Pre-heat	120~150°C	180~200°C	Soldering time	3sec Max (one time only)
Pre-heat time	120sec Max	120sec Max		
Peak temperature	240°C Max	260°C Max		
Soldering time	10sec Max	10sec Max		
Condition	refer to Temperature-profile 1	refer to Temperature-profile 2		

*After reflow soldering rapid cooling should be avoided.

[Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.

< 1 : Lead Solder >



< 2 : Lead-free Solder >

